



## Material Content Data Sheet



<b>Sales Product Name</b>		BFR 750L3RH E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000365021						
<b>Package</b>		PG-TSLP-3-9		<b>Weight*</b>		0.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.14		1382	
	noble metal	gold	7440-57-5	0.003	0.54		5359	
	inorganic material	silicon	7440-21-3	0.020	3.97	4.65	39710	46451
leadframe	non noble metal	nickel	7440-02-0	0.131	26.12	26.12	261200	261200
wire	noble metal	gold	7440-57-5	0.009	1.73	1.73	17277	17277
encapsulation	organic material	carbon black	1333-86-4	0.003	0.62		6195	
	plastics	epoxy resin	-	0.042	8.36		83627	
	inorganic material	silicondioxide	60676-86-0	0.266	52.96	61.94	529640	619462
leadfinish	noble metal	gold	7440-57-5	0.011	2.11	2.11	21121	21121
plating	noble metal	silver	7440-22-4	0.017	3.45	3.45	34489	34489
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com